

Claims

What is claimed is:

1. A solder plating system, comprising:
5 a solder plating machine;
a wash fluid supply system for supplying wash fluid to the solder
plating machine;
a pressure sensor for monitoring the pressure of wash fluid supplied by
the wash fluid supply system; and
10 a switch control system for automatically switching an alarm based on
one or more readings supplied by the pressure sensor.
2. The solder plating system of claim 1, wherein the switch control
system automatically shuts down the solder plating machine based on one or more
15 readings supplied by the pressure sensor.
3. The solder plating system of claim 1, wherein the switch control
system activates an alarm when the wash fluid pressure drops below a first value.
- 20 4. The solder plating system of claim 3, wherein the switch control
system automatically shuts down the solder plating machine when the wash fluid
pressure drops below a second value.
5. The solder plating system of claim 1, wherein the switch control
25 system includes a memory that retains readings supplied by the pressure sensor.
6. The solder plating system of claim 5, wherein the switch control
system further comprises an expert system.

7. The solder plating system of claim 5, wherein the switch control system automatically shuts down the solder plating machine based on a reading supplied by the pressure sensor together with one or more retained readings.

5 8. A solder plating system, comprising:
a solder plating machine;
a wash fluid supply system for supplying wash fluid to the solder
plating machine;
means for monitoring a pressure of the wash fluid supplied by the wash
10 fluid supply system; and
means for triggering an alarm when the wash fluid pressure varies
outside preset parameters.

15 9. The solder plating system of claim 8, further comprising means for
shutting down the solder plating machine automatically when the wash fluid pressure
varies outside preset parameters.

20 10. A method of operating a solder plating system, comprising:
supplying wash fluid for a solder plating machine;
obtaining pressure readings for the wash fluid supplied to the solder
plating machine; and
automatically activating an alarm based on one or more of the readings.

25 11. The method of claim 10, wherein automatically activating the alarm is
based on a reading that indicates the pressure is below a threshold value.

30 12. The method of claim 10, further comprising retaining readings relating
to the pressure for the wash fluid and wherein automatically activating the alarm
depends in part on retained readings.

13. The method of claim 10, wherein automatically activating an alarm based on one or more of the readings comprises using an expert system to decide whether to activate the alarm

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14. A method of operating a solder plating system, comprising:
supplying wash fluid for the solder plating machine;
obtaining readings relating to a pressure for the wash fluid supplied to the solder plating machine; and

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automatically shutting down the solder plating machine based on one or more of the readings.

15. The method of claim 14, wherein automatically shutting down the solder plating machine is based on a reading that indicates the pressure is below a threshold value

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16. The method of claim 14, wherein automatically shutting down the solder plating machine based on one or more of the readings comprises using an expert system to decide whether to shut down the solder plating machine.